

Specification of Thermoelectric Module

TEC3-71-31-17-09S

Description

The TEC3-71-31-17-09S is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 71-31-17 couples module in size of 22mm×22mm (top)/44mm ×44mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

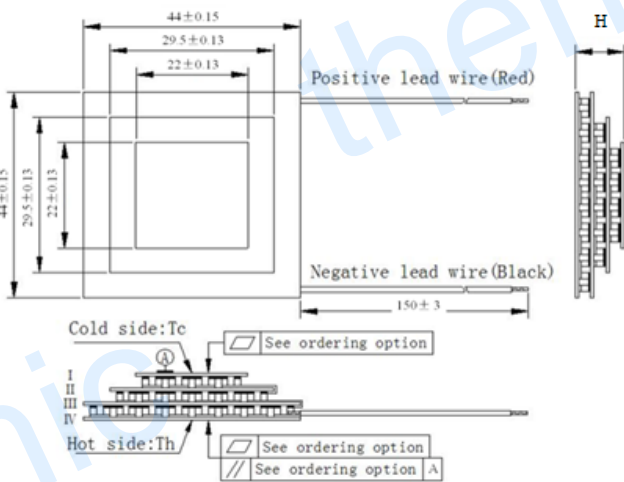
Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	100	112	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	8.2	9.2	Voltage applied to the module at DT _{max}
I _{max} (Amps)	8.5	8.5	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	16.8	18.5	Cooling capacity at cold side of the module under DT=0°C
AC resistance (Ohms)	0.88	0.97	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

1. T100: BiSn (Melting Point=138 °C)
2. T200: CuSn (Melting Point= 227 °C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)(AlO)
2. Beryllia (BeO)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

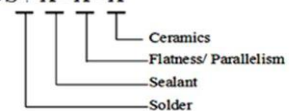
Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 12.95 ±0.3	0: 0.15/0.2	150±3/Specify
TF	1: 12.95±0.15	1: 0.13/0.18	150±3/Specify

Eg. TF01: Thickness 12.95±0.3 (mm) and Flatness/ Parallelism 0.13/0.18 (mm)

Naming for the Module

TEC3-71-31-17-09S- -X - X - X



TEC3-71-31-17-09S-T100-NS-TF01-AlO

T100: BiSn(T_{mel}=138°C)

NS: No sealing

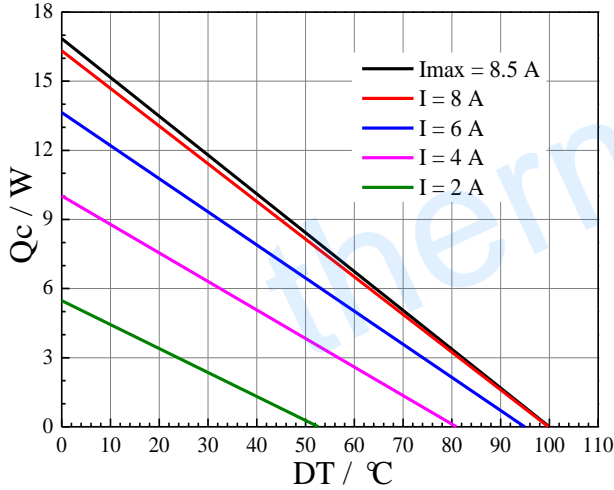
TF01: Thickness ± 0.3 (mm) and Flatness/ Parallelism 0.13/0.18 (mm)

AlO: Alumina white 96%

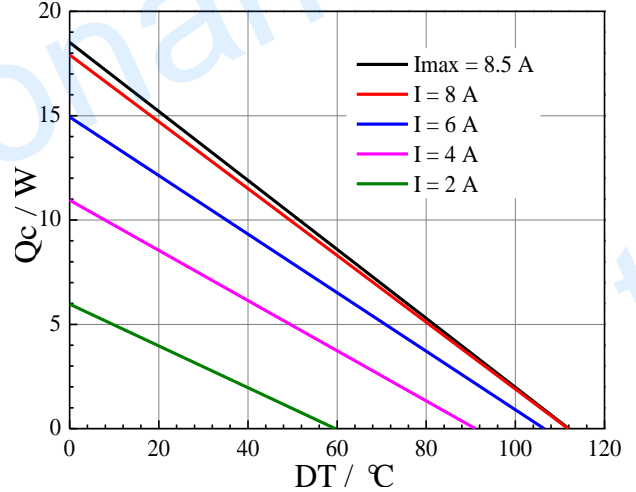
Specification of Thermoelectric Module

TEC3-71-31-17-09S

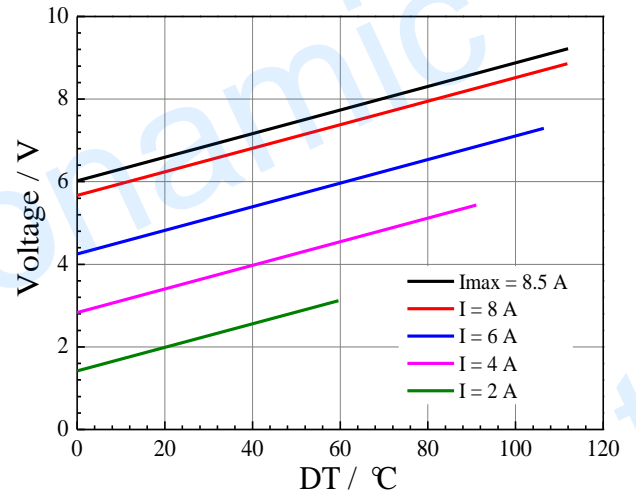
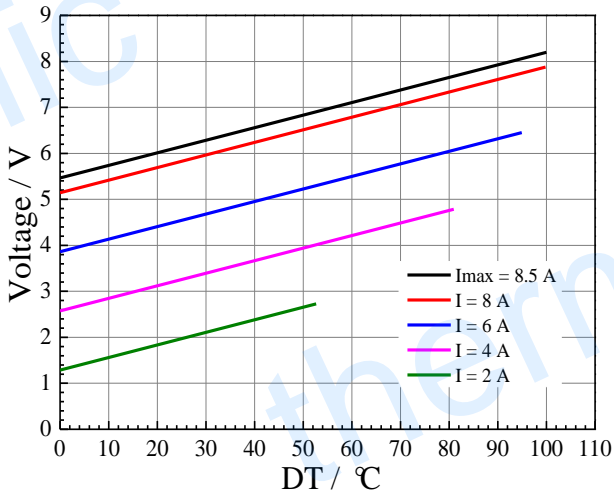
Performance Curves at $T_h=27\text{ }^\circ\text{C}$



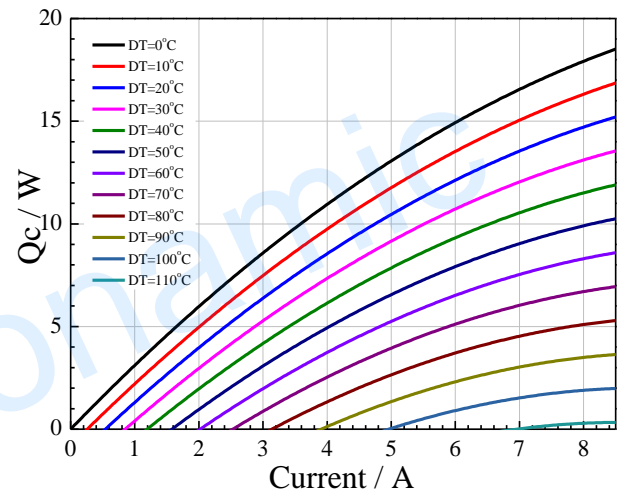
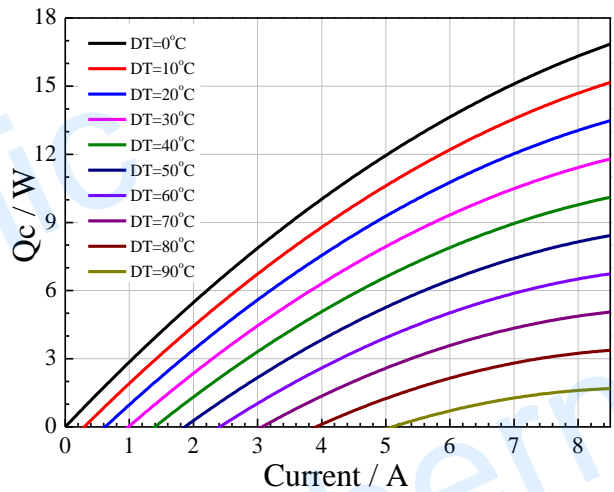
Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

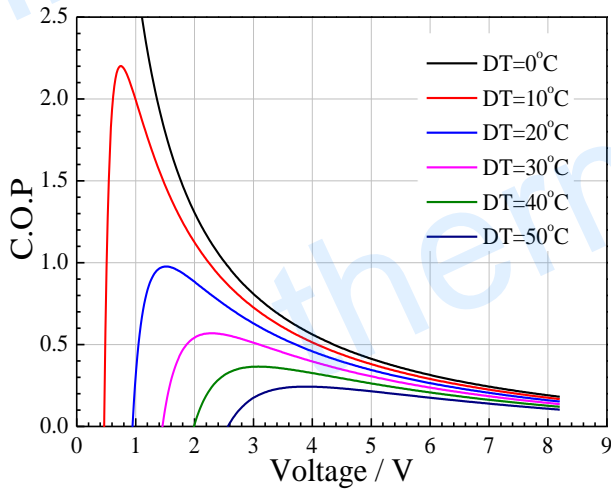


Standard Performance Graph $Q_c = f(I)$

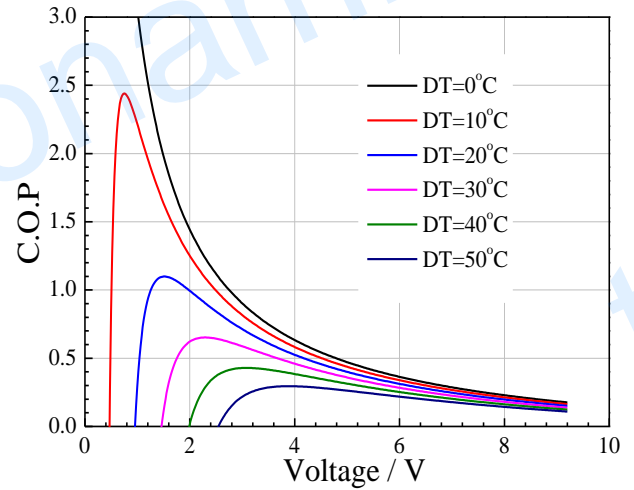
Specification of Thermoelectric Module

TEC3-71-31-17-09S

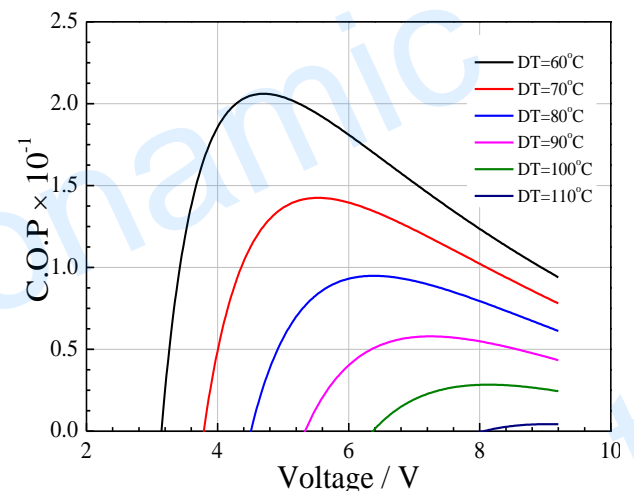
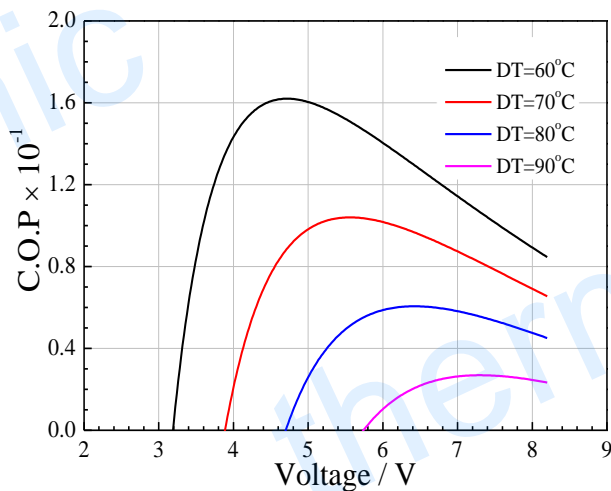
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 50 °C



Standard Performance Graph COP = f(V) of DT ranged from 60 to 90/110 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Cold side of the module stuck on the object being cooled
- Hot side of the module mounted on a heat radiator
- Storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.